

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
N	1	35.76mil (1.000mm)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r130_170n101_356r95			
A	2	28.92mil (0.740mm)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r380_150n106_305r79			
□	2	40.16mil (1.020mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c09n102			
○	2	50.00mil (1.270mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c127n127			
○	2	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c221n160			
⊗	2	96.46mil (2.450mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c200n245			
⊗	2	105.96mil (2.690mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c-127n269			
○	2	125.98mil (3.200mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c320n320a320p0			
○	4	118.11mil (3.000mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c300n300a315			
▽	5	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c104n71			
B	6	47.24mil (1.200mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)			
⊗	20	15.00mil (0.381mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c64n38a0a0			
D	32	25.00mil (0.635mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c104n64n104a0			
□	32	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)			
*	48	15.75mil (0.400mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c69n10a0a0			
○	52	66.93mil (1.700mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c260n170a260p0			
○	54	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)			
C	58	25.53mil (0.750mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)			
V	59	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)			
E	168	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v61n30a0a0			
E	1980	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	(Mixed)	Rounded	(Mixed)			
2543 Total											

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size + Slot length as defined in the PCB layout

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric 1	Megtron6	5.70mil	3.23	
2	L2 GND	CF-004	1.40mil		
	Dielectric 3	FR4-370HR	3.00mil	3.72	
3	L3 PWR	CF-004	2.76mil		
	Dielectric 5	FR4-370HR	3.00mil	3.86	
4	L4 GND	CF-004	1.40mil		
	Dielectric 7	FR4-370HR	3.00mil	3.72	
5	L5 PWR/SIG	CF-004	1.38mil		
	Dielectric 11	FR4-370HR	3.00mil	3.86	
6	L6 GND	CF-004	1.38mil		
	Dielectric 15	FR4-370HR	4.80mil	3.92	
7	L7 SIGNAL	CF-004	0.69mil		
	Dielectric 9	FR4-370HR	4.80mil	3.92	
8	L8 GND	CF-004	1.38mil		
	Dielectric 13	FR4-370HR	4.80mil	3.92	
9	L9 GND	CF-004	1.38mil		
	Dielectric1	FR4-370HR	4.80mil	3.92	
10	L10 SIGNAL	CF-004	1.38mil		
	Dielectric 14	FR4-370HR	4.80mil	3.92	
11	L11 GND	CF-004	1.38mil		
	Dielectric 10	FR4-370HR	4.80mil	3.92	
12	L12 SIGNAL	CF-004	0.69mil		
	Dielectric 16	FR4-370HR	4.80mil	3.92	
13	L13 GND	CF-004	1.38mil		
	Dielectric 12	FR4-370HR	3.00mil	3.86	
14	L14 PWR	CF-004	1.38mil		
	Dielectric 8	FR4-370HR	3.00mil	3.72	
15	L15 GND	CF-004	1.40mil		
	Dielectric 6	FR4-370HR	3.00mil	3.86	
16	L16 PWR/SIG	CF-004	2.76mil		
	Dielectric 4	FR4-370HR	3.00mil	3.72	
17	L16 GND	CF-004	1.40mil		
	Dielectric 2	Megtron6	5.70mil	3.23	
18	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				
Total board thickness:			96.11mil		

M10 Fab Notes

DESIGN INFORMATION

MIN. TRACK WIDTH: 3.5 MIL
MIN. CLEARANCE: 4 MIL
MIN. VIA PAD SIZE: 20 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:

☒ HYBRID STACKUP ☐ UNIFORM STACKUP

☒ ISOLA FR4-370HR

☐ Megtron 4 **OR** Isola I-Speed

☒ Megtron6 **OR** Isola MT-40 **OR** Nelco MW-1000

☐ OTHER

THICKNESS: ☐ 62 MIL (1.6mm) +/-10% ☒ OTHER 95 MIL +/-10%

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/-

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/-

DRILLING:

REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES

PTH COPPER THICKNESS: ☒ 20-30 um ☐ OTHER

BOARD FINISH:

SILKSCREEN: ☒ TOP ☒ BOTTOM

SILKSCREEN COLOR: ☒ WHITE ☐ OTHER

SOLDER RESIST COLOR: ☐ GREEN ☒ OTHER DARK GREEN
☒ MATTE ☐ SEMI-GLOSS

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENEPIG
☐ IMM. TIN/SILVER OR EQUIV ☐ HARD GOLD (30u)
☐ OTHER

ARRAY/PANEL: ☐ CUT AND TRIM PER M1 BOARD OUTLINE
☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3
☒ RoHS ☐ OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL D NUMBER

ADDITIONAL REQUIREMENTS:

MICROSECTION: ☐ YES

BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

☒ 16 MIL & SMALLER VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE

☒ OUTER LAYER TRACKS 12.1 MIL WIDE REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE

☒ OUTER LAYER TRACKS 7.4 MIL WIDE WITH 5 MIL SPACE REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

☐ INNER LAYERS TRACKS XX MIL WIDE REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE

☒ INNER LAYER TRACKS 3.5 MIL WIDE WITH 6.5 MIL SPACE REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE



PROJECT TITLE:
ADC34RF7xEUM

DESIGNED FOR:
Not For Public Release

FILE NAME:
ADC34RF7x_REU_A_PcbDoc

ENGINEER:

CW

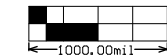
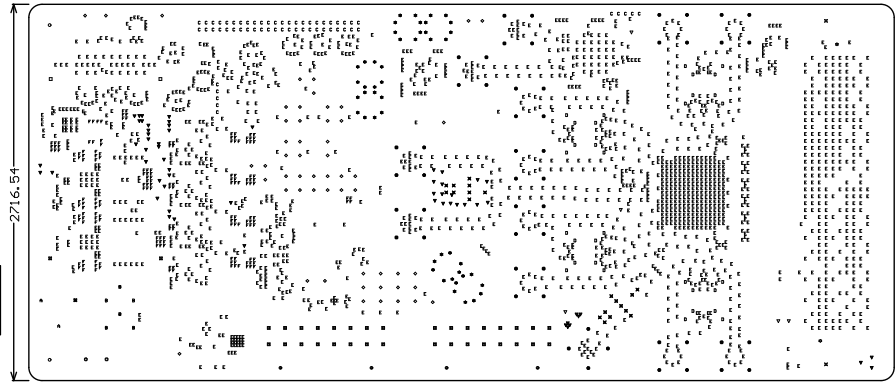
LAYOUT BY:

CW/GR

SCALE: 1.00

ALUM DESIGNER VERSION:

24.7.2.38



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: -	REV: A	SUN REV: cfec0883921a2ab84ee9aba05e8e2aa5b45f222 [Locally Modified]
LAYER NAME = Fabrication Drawing			
PLOT NAME = Fabrication Drawing	GENERATED : 3/13/2025 2:19:09 PM	TEXAS INSTRUMENTS	

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